Linde Electronics List of Gases

	CLEANING	DEPO-SITION	DOPING	ETCH	ANNEALING	LITHO-GRAPHY	PURGING
Ar (Argon)							●
$Ar/F_2/Ne$ (Argon/Fluorine/Neon - ArF laser)						●	
Ar/Xe/Ne (Argon/Xenon/Neon - ArF laser)						●	
AsH_3 (Arsine)		●	●				
BF_3 (Boron trifluoride)			●				
$^{11}BF_3$ (Boron-11 trifluoride)			●				
$^{11}B_2H_6$ (Enriched diborane)			●				
B_2H_6 (Diborane)			●				
BCl_3 (Boron tricholoride)				●			
C_2F_6 (Hexafluoroethane) Halocarbon 116	●	●		●			
C_2H_2 (Acetylene)		●					
C_3F_8 (Octafluoropropane) Halocarbon 218				●			
C_3H_6 (Propylene)		●					
C_4F_6 (Hexafluoro-3-butadiene) Halocarbon 2316				●			
C_4F_8 (Octofluorocyclo butane) Halocarbon 318				●			
C_5F_8 (Octofluorocyclo pentene) Halocarbon c1418				●			
CF_4 (Carbon tetrafluoride) Halocarbon 14	●			●			

	CLEANING	DEPO-SITION	DOPING	ETCH	ANNEALING	LITHO-GRAPHY	PURGING
CH_2F_2 (Difluoromethane) Halocarbon 32				●			
C_2HF_5 (Pentafluoroethane)				●			
CH_3F (Fluoromethane) Halocarbon 41				●			
CH_4 (Methane)		●		●			
CHF_3 (Trifluoromethane) Halocarbon 23				●			
Cl_2 (Chlorine)	●			●			
ClF_3 (Chlorine trifluoride)	●						
CO (Carbon monoxide)		●		●			
CO_2 (Carbon dioxide)				●		●	
COS (Carbonyl sulfide)		●					
D_2 (Deuterium)					●		
DEZ (Diethylzinc)		●	●				
F_2 (Fluorine)	●						
F_2/N_2 (Fluorine/Nitrogen)	●						
$GeCl_4$ (Germanium tetrachloride)		●					
GeH_4 (Germane)		●	●				
He (Helium)							●
H_2 (Hydrogen)					●	●	●
H_2S (Hydrogen sulfide)		●					

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	CLEANING	DEPO-SITION	DOPING	ETCH	ANNEALING	LITHO-GRAPHY	PURGING
H_2Se (Hydrogen selenide)	●						
HBr (Hydrogen bromide)				●			
HCDS (Hexachlorodisilane)		●					
HCl (Hydrogen chloride)		●		●			
HF (Hydrogen fluoride)				●			
Kr (Krypton)				●		●	
$Kr/F_2/Ne$ (Krypton/Fluorine/Neon - KrF laser)						●	
Kr/Ne (Krypton/Neon - KrF laser)						●	
N_2 (Nitrogen)							●
N_2O (Nitrous oxide)		●		●			
ND_3 (Deuterated ammonia)		●					
Ne (Neon)						●	
$Ne/HCl/H_2$ mixture (Neon/Hydrogen chloride/Hydrogen)						●	
NF_3 (Nitrogen trifluoride)	●			●			
NH_3 (Ammonia)		●					
NO (Nitric oxide)		●		●			
O_2 (Oxygen)	●	●		●			
PH_3 (Phosphine)		●	●				

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	CLEANING	DEPO-SITION	DOPING	ETCH	ANNEALING	LITHO-GRAPHY	PURGING
SF_6 (Sulfur hexafluoride)	●			●			
Si_2Cl_6 (HCDS - Hexachlorodisilane)		●					
Si_2H_6 (Disilane)		●					
$SiCl_4$ (Tetrachlorosilane – silicon tetrachloride)		●					
SiD_4 (Deuterated silane)		●					
SiF_4 (Tetrafluorosilane - also know as silicon tetrafluoride)		●		●			
SiH_2Cl_2 (Dichlorosilane)		●					
SiH_4 (Silane)		●					
$SiHCl_3$ (TCS - Trichlorosilane)		●					
SO_2 (Sulfur dioxide)		●					
TEA (Triethylaluminum)		●					
TMA (Trimethylaluminum)		●					
TMB (Trimethylboron)			●				
TMS (3MS - Trimethylsilane)		●					
WF_6 (Tungsten hexafluoride)		●					
Xe (Xenon)				●		●	
XeF_2 (Xenon difluoride)				●			
Mixtures (calibration, etc.)							

www.linde.com/electronics
For more information, please contact us at electronicsinfo@linde.com.

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